IPC  ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IF	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	ials and Mfc Information			
upplier Infor	mation														
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2023-06	2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number		Mfr Item Number		Mfr Item Name		Effective Date	Version	n	Manufacturing Site		Weight*	UOM	Unit Type	
		LC89091	JA-H	DIR			2023-06-08				3	80.0	mg	Each	
lanufacturing	g Proccess Informat	ion						·			·			·	
Terminal Plating / Grid Array Material T			Ferminal Base Alloy J-STD-020 MSL F		Rating	Peak Process Body Temperature		re Max Time at Peak	Temperat	ure Num	ber of Reflow Cyc	eles			
contains Bi		C	CU Alloy 3			260   C   30		30	secon	ds 3					
omments															
TTENTION: MS	SL 3 Rated item requires	Bake and D	ry Pack (afte	r electrical test)											
or more informa	tion regarding material o	composition <b>1</b>	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct omponents, the declaration shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.3232	mg
			Supplier	Polyimide	Proprietary Data		0.0068	mg
Die Attach	0.32	mg	Supplier	Silver (Ag)	7440-22-4		0.2272	mg
			Supplier	Epoxy resins	129915-35-1		0.0928	mg
Lead Frame	6.56	mg	Supplier	Zinc (Zn)	7440-66-6		0.0085	mg
			Supplier	Iron (Fe)	7439-89-6		0.1542	mg
			Supplier	Copper (Cu)	7440-50-8		6.3921	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0052	mg
Mold Compound-Black	70.28	mg		Epoxy Phenol Resin	proprietary data		8.4336	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2811	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		59.4569	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		2.1084	mg
Plating	1.13	mg	В	Bismuth (Bi)	7440-69-9		0.0226	mg
			Supplier	Tin (Sn)	7440-31-5		1.1074	mg
Wire Bond - Au	0.38	mg	Supplier	Gold (Au)	7440-57-5		0.38	mg